 <p>U.S. Department of Commerce, Patent and Trademark Office</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p>(Use several sheets if necessary)</p>	Application No.:	10/722,724
	Filing Date:	November 25, 2003
	First Named Inventor:	Peter G. Borden
	Group Art Unit:	2877
	Examiner Name:	Rosenberger
	Confirmation No.:	7346
	Attorney Docket No.:	BOX004-1C US

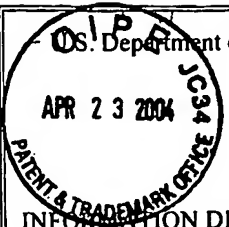
U.S. Patent Documents

*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
<i>RA</i>	1.	4,854,710	8/8/89	Opsal et al.	356	432	
<i>RA</i>	2.	6,489,801	12/3/02	Borden et al.	324	766	
<i>RA</i>	3.	5,966,019	10/12/99	Borden	324	752	
<i>RA</i>	4.	6,323,951	11/27/01	Borden et al.	356	502	
<i>RA</i>	5.	6,426,644	7/30/02	Borden et al.	324	765	
<i>RA</i>	6.	4,952,063	8/27/90	Opsal et al.	356	432	
<i>RA</i>	7.	5,042,951	8/27/91	Gold et al.	356	369	
<i>RA</i>	8.	5,042,952	8/27/1991	Opsal et al.	356	432	
<i>RA</i>	9.	5,159,412	10/27/92	Willenborg et al.	356	445	
<i>RA</i>	10.	5,181,080	1/19/93	Fanton et al.	356	381	
<i>RA</i>	11.	5,228,776	7/20/93	Smith et al.	374	5	
<i>RA</i>	12.	4,255,971	3/17/81	Rosencwaig	73	606	
<i>RA</i>	13.	4,579,463	4/1/86	Rosencwaig et al.	374	57	
<i>RA</i>	14.	4,632,561	12/30/86	Rosencwaig et al.	356	432	
<i>RA</i>	15.	4,636,088	1/13/87	Rosencwaig et al.	374	5	
<i>RA</i>	16.	4,750,822	6/14/88	Rosencwaig et al.	324	445	
<i>RA</i>	17.	6,049,220	4/11/00	Borden et al.	324	765	
<i>RA</i>	18.	6,483,594	11/19/02	Borden et al.	356	502	
<i>RA</i>	19.	5,652,716	7/29/97	Battersby	703	13	
<i>RA</i>	20.	5,761,082	6/2/98	Miura-Mattausch	703	14	
<i>RA</i>	21.	4,996,659	2/26/91	Yamaguchi et al.	714	736	
<i>RA</i>	22.	6,154,280	11/2/00	Borden	356	376	
<i>RA</i>	23.	6,054,868	4/25/00	Borden et al.	324	752	
<i>RA</i>	24.	5,883,518	3/16/99	Borden	324	752	
<i>RA</i>	25.	5,877,860	3/2/99	Borden	356	376	

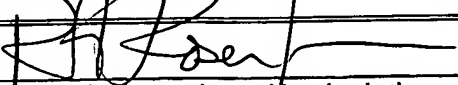
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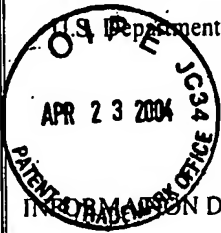
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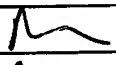
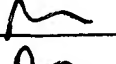

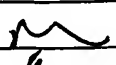
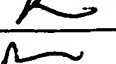
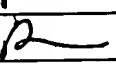
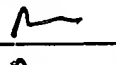

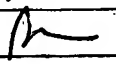
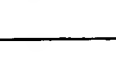

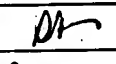
* Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant.

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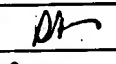
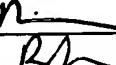
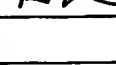
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M	29.	2002/0126732A1	9/12/02	Shakouri et al.	374	130	
M	30.	2003/0155927A1	8/21/03	Pinto et al.	324	501	
M	31.	6,489,624	12/3/02	Ushio et al.	250	559	
M	32.	6,486,965	11/26/02	Kim	356	626	
M	33.	5,741,614	4/21/98	McCoy et al.	430	30	
M	34.	6,327,035	12/4/01	Li et al.	356	432	
M	35.	5,454,004	9/26/95	Leger	372	99	
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M	51.	4,243,327	1/6/81	Frosch et al.	356	432	
M	52.	3,930,730	1/6/76	Laurens et al.	356	106	

Examiner: 	Date Considered: C/4/04
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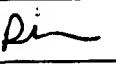
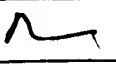
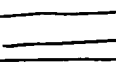
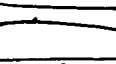

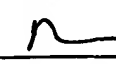
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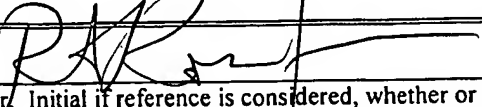
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	56.	5,408,327	4/18/95	Geiler et al.	356	432	
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	58.	6,559,942	5/6/03	Sui et al.	356	369	
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	62.	3,462,602	8/16/67	Apple	250	83	
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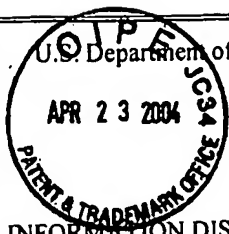
65. Foreign Patent Documents

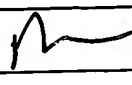

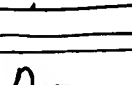
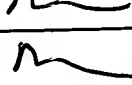
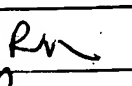
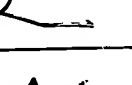

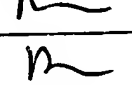
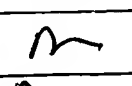
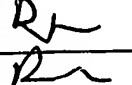
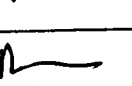
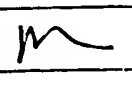
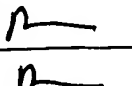
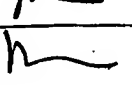
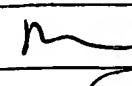
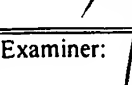
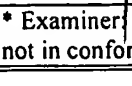


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	66.	2000009443A	1/1/2000	Japan	G01B			
	67.	05006929A	Jan-93	Japan	H01L	21/66		

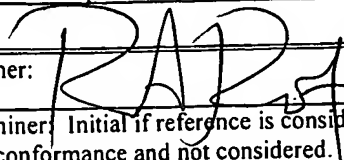
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)

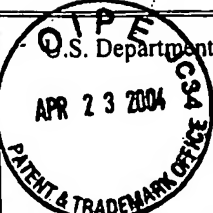
	68.	Intl Prel Search Report PCT/US03/29993
	69.	Jackson, "Classical Electrodynamics", John Wiley & Sons, Inc., (month unavailable), 1967, pp. 222-226
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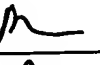



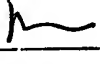
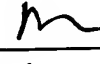





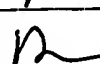
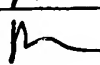
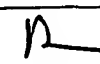

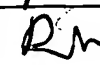
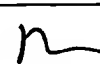
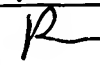
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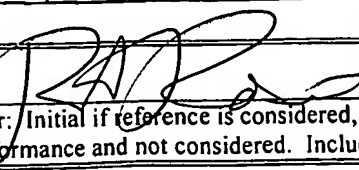
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	74.	Opsal et al. "Thermal-Wave Detection and Thin-Film Thickness Measurements with Laser Beam Deflection", Applied Optics, Vol. 22, No. 20, Oct. 1983, pp. 3169-3176
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	Filing Date:	November 25, 2003
	First Named Inventor:	Peter G. Borden
	Group Art Unit:	2877
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